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Understanding Embedded - FPGAs (Field Programmable Gate Array)

Embedded - FPGAs, or Field Programmable Gate Arrays, are advanced integrated circuits that offer unparalleled flexibility and performance for digital systems. Unlike traditional fixed-function logic devices, FPGAs can be programmed and reprogrammed to execute a wide array of logical operations, enabling customized functionality tailored to specific applications. This reprogrammability allows developers to iterate designs quickly and implement complex functions without the need for custom hardware.

Applications of Embedded - FPGAs

The versatility of Embedded - FPGAs makes them indispensable in numerous fields. In telecommunications.

Details

Product Status	Obsolete
Number of LABs/CLBs	360
Number of Logic Elements/Cells	2880
Total RAM Bits	20480
Number of I/O	291
Number of Gates	116000
Voltage - Supply	3V ~ 3.6V
Mounting Type	Surface Mount
Operating Temperature	0°C ~ 70°C (TA)
Package / Case	484-BBGA
Supplier Device Package	484-FBGA (23x23)
Purchase URL	https://www.e-xfl.com/product-detail/intel/epf10k50vfc484-1

- Flexible interconnect
 - FastTrack® Interconnect continuous routing structure for fast, predictable interconnect delays
 - Dedicated carry chain that implements arithmetic functions such as fast adders, counters, and comparators (automatically used by software tools and megafunctions)
 - Dedicated cascade chain that implements high-speed, high-fan-in logic functions (automatically used by software tools and megafunctions)
 - Tri-state emulation that implements internal tri-state buses
 - Up to six global clock signals and four global clear signals
- Powerful I/O pins
 - Individual tri-state output enable control for each pin
 - Open-drain option on each I/O pin
 - Programmable output slew-rate control to reduce switching noise
 - FLEX 10KA devices support hot-socketing
- Peripheral register for fast setup and clock-to-output delay
- Flexible package options
 - Available in a variety of packages with 84 to 600 pins (see [Tables 4 and 5](#))
 - Pin-compatibility with other FLEX 10K devices in the same package
 - FineLine BGA™ packages maximize board space efficiency
- Software design support and automatic place-and-route provided by Altera development systems for Windows-based PCs and Sun SPARCstation, HP 9000 Series 700/800 workstations
- Additional design entry and simulation support provided by EDIF 2.0 and 3.0 netlist files, library of parameterized modules (LPM), DesignWare components, Verilog HDL, VHDL, and other interfaces to popular EDA tools from manufacturers such as Cadence, Exemplar Logic, Mentor Graphics, OrCAD, Synopsys, Synplicity, VeriBest, and Viewlogic

Notes to tables:

- (1) FLEX 10K and FLEX 10KA device package types include plastic J-lead chip carrier (PLCC), thin quad flat pack (TQFP), plastic quad flat pack (PQFP), power quad flat pack (RQFP), ball-grid array (BGA), pin-grid array (PGA), and FineLine BGA™ packages.
- (2) This option is supported with a 256-pin FineLine BGA package. By using SameFrame pin migration, all FineLine BGA packages are pin compatible. For example, a board can be designed to support both 256-pin and 484-pin FineLine BGA packages. The Altera software automatically avoids conflicting pins when future migration is set.

General Description

Altera's FLEX 10K devices are the industry's first embedded PLDs. Based on reconfigurable CMOS SRAM elements, the Flexible Logic Element MatriX (FLEX) architecture incorporates all features necessary to implement common gate array megafunctions. With up to 250,000 gates, the FLEX 10K family provides the density, speed, and features to integrate entire systems, including multiple 32-bit buses, into a single device.

FLEX 10K devices are reconfigurable, which allows 100% testing prior to shipment. As a result, the designer is not required to generate test vectors for fault coverage purposes. Additionally, the designer does not need to manage inventories of different ASIC designs; FLEX 10K devices can be configured on the board for the specific functionality required.

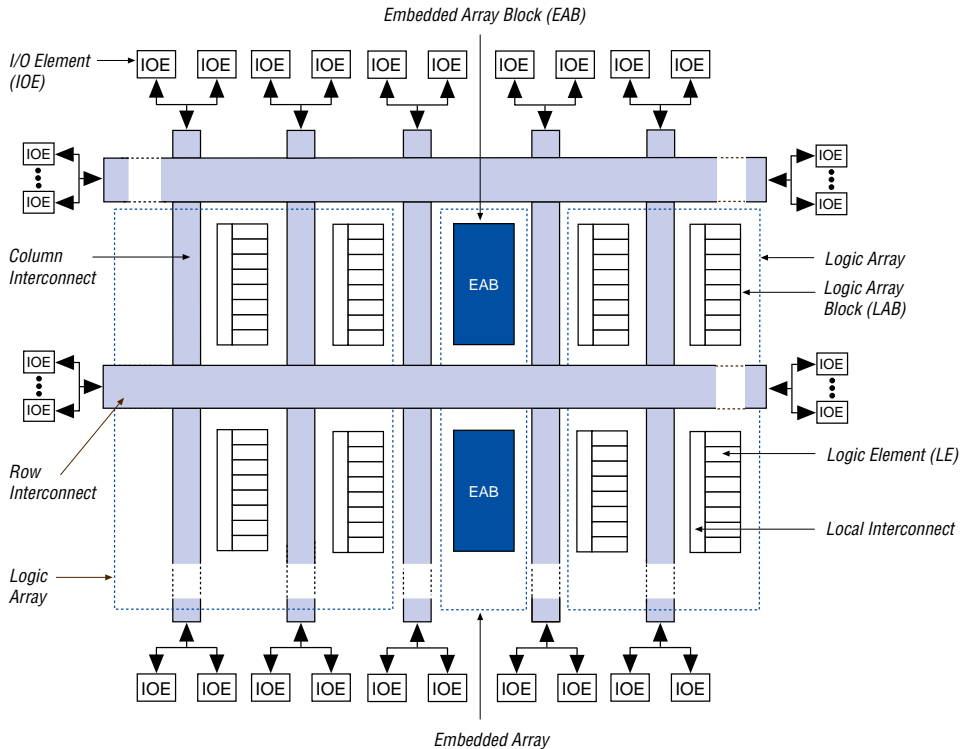
Table 6 shows FLEX 10K performance for some common designs. All performance values were obtained with Synopsys DesignWare or LPM functions. No special design technique was required to implement the applications; the designer simply inferred or instantiated a function in a Verilog HDL, VHDL, Altera Hardware Description Language (AHDL), or schematic design file.

Table 6. FLEX 10K & FLEX 10KA Performance

Application	Resources Used		Performance				Units
	LEs	EABs	-1 Speed Grade	-2 Speed Grade	-3 Speed Grade	-4 Speed Grade	
16-bit loadable counter (1)	16	0	204	166	125	95	MHz
16-bit accumulator (1)	16	0	204	166	125	95	MHz
16-to-1 multiplexer (2)	10	0	4.2	5.8	6.0	7.0	ns
256 × 8 RAM read cycle speed (3)	0	1	172	145	108	84	MHz
256 × 8 RAM write cycle speed (3)	0	1	106	89	68	63	MHz

Notes:

- (1) The speed grade of this application is limited because of clock high and low specifications.
- (2) This application uses combinatorial inputs and outputs.
- (3) This application uses registered inputs and outputs.

Figure 1. FLEX 10K Device Block Diagram

FLEX 10K devices provide six dedicated inputs that drive the flipflops' control inputs to ensure the efficient distribution of high-speed, low-skew (less than 1.5 ns) control signals. These signals use dedicated routing channels that provide shorter delays and lower skews than the FastTrack Interconnect. Four of the dedicated inputs drive four global signals. These four global signals can also be driven by internal logic, providing an ideal solution for a clock divider or an internally generated asynchronous clear signal that clears many registers in the device.

Embedded Array Block

The EAB is a flexible block of RAM with registers on the input and output ports, and is used to implement common gate array megafunctions. The EAB is also suitable for functions such as multipliers, vector scalars, and error correction circuits, because it is large and flexible. These functions can be combined in applications such as digital filters and microcontrollers.

The programmable flipflop in the LE can be configured for D, T, JK, or SR operation. The clock, clear, and preset control signals on the flipflop can be driven by global signals, general-purpose I/O pins, or any internal logic. For combinatorial functions, the flipflop is bypassed and the output of the LUT drives the output of the LE.

The LE has two outputs that drive the interconnect; one drives the local interconnect and the other drives either the row or column FastTrack Interconnect. The two outputs can be controlled independently. For example, the LUT can drive one output while the register drives the other output. This feature, called register packing, can improve LE utilization because the register and the LUT can be used for unrelated functions.

The FLEX 10K architecture provides two types of dedicated high-speed data paths that connect adjacent LEs without using local interconnect paths: carry chains and cascade chains. The carry chain supports high-speed counters and adders; the cascade chain implements wide-input functions with minimum delay. Carry and cascade chains connect all LEs in an LAB and all LABs in the same row. Intensive use of carry and cascade chains can reduce routing flexibility. Therefore, the use of these chains should be limited to speed-critical portions of a design.

Carry Chain

The carry chain provides a very fast (as low as 0.2 ns) carry-forward function between LEs. The carry-in signal from a lower-order bit drives forward into the higher-order bit via the carry chain, and feeds into both the LUT and the next portion of the carry chain. This feature allows the FLEX 10K architecture to implement high-speed counters, adders, and comparators of arbitrary width efficiently. Carry chain logic can be created automatically by the Compiler during design processing, or manually by the designer during design entry. Parameterized functions such as LPM and DesignWare functions automatically take advantage of carry chains.

Carry chains longer than eight LEs are automatically implemented by linking LABs together. For enhanced fitting, a long carry chain skips alternate LABs in a row. A carry chain longer than one LAB skips either from even-numbered LAB to even-numbered LAB, or from odd-numbered LAB to odd-numbered LAB. For example, the last LE of the first LAB in a row carries to the first LE of the third LAB in the row. The carry chain does not cross the EAB at the middle of the row. For instance, in the EPF10K50 device, the carry chain stops at the eighteenth LAB and a new one begins at the nineteenth LAB.

LE Operating Modes

The FLEX 10K LE can operate in the following four modes:

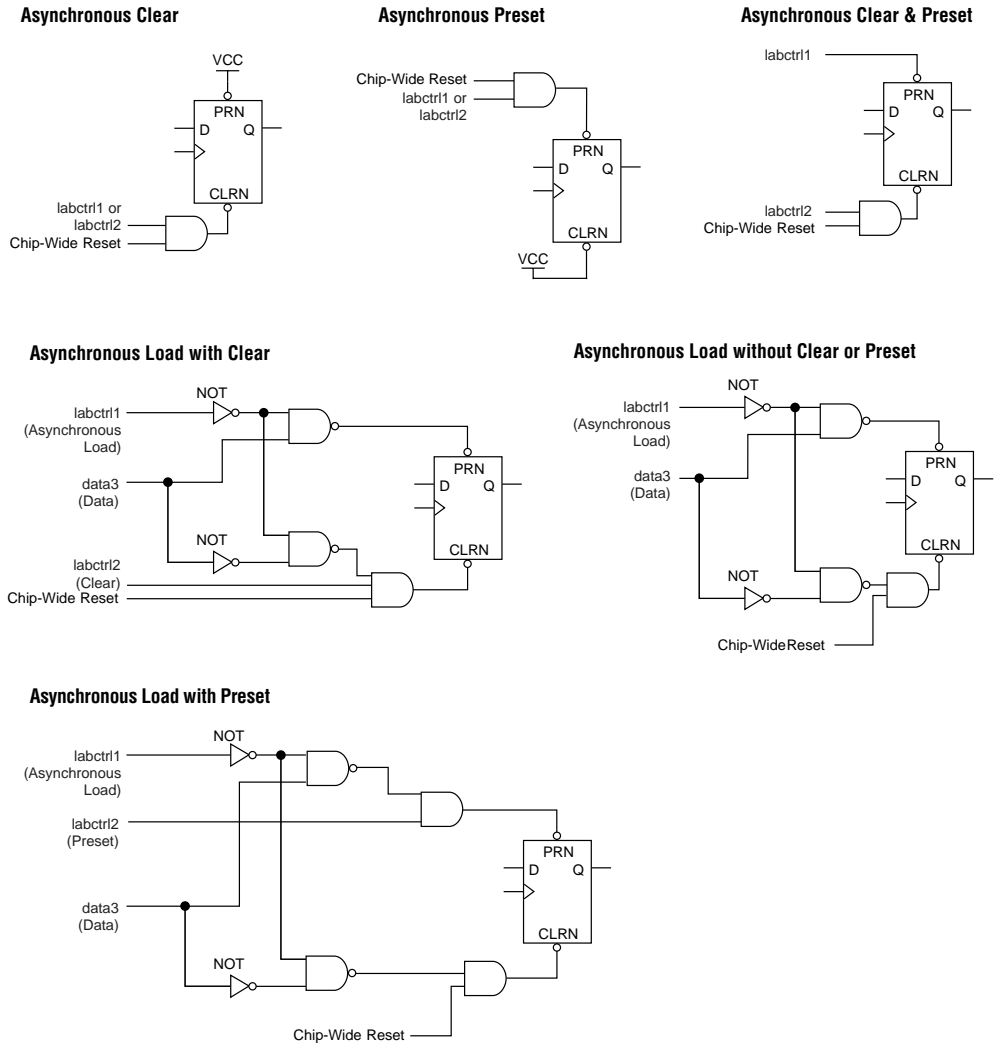
- Normal mode
- Arithmetic mode
- Up/down counter mode
- Clearable counter mode

Each of these modes uses LE resources differently. In each mode, seven available inputs to the LE—the four data inputs from the LAB local interconnect, the feedback from the programmable register, and the carry-in and cascade-in from the previous LE—are directed to different destinations to implement the desired logic function. Three inputs to the LE provide clock, clear, and preset control for the register. The Altera software, in conjunction with parameterized functions such as LPM and DesignWare functions, automatically chooses the appropriate mode for common functions such as counters, adders, and multipliers. If required, the designer can also create special-purpose functions which use a specific LE operating mode for optimal performance.

The architecture provides a synchronous clock enable to the register in all four modes. The Altera software can set DATA1 to enable the register synchronously, providing easy implementation of fully synchronous designs.

Figure 9 shows the LE operating modes.

Figure 10. LE Clear & Preset Modes



Asynchronous Clear

The flipflop can be cleared by either LABCTRL1 or LABCTRL2. In this mode, the preset signal is tied to V_{CC} to deactivate it.

FastTrack Interconnect

In the FLEX 10K architecture, connections between LEs and device I/O pins are provided by the FastTrack Interconnect, which is a series of continuous horizontal and vertical routing channels that traverse the device. This global routing structure provides predictable performance, even in complex designs. In contrast, the segmented routing in FPGAs requires switch matrices to connect a variable number of routing paths, increasing the delays between logic resources and reducing performance.

The FastTrack Interconnect consists of row and column interconnect channels that span the entire device. Each row of LABs is served by a dedicated row interconnect. The row interconnect can drive I/O pins and feed other LABs in the device. The column interconnect routes signals between rows and can drive I/O pins.

A row channel can be driven by an LE or by one of three column channels. These four signals feed dual 4-to-1 multiplexers that connect to two specific row channels. These multiplexers, which are connected to each LE, allow column channels to drive row channels even when all eight LEs in an LAB drive the row interconnect.

Each column of LABs is served by a dedicated column interconnect. The column interconnect can then drive I/O pins or another row's interconnect to route the signals to other LABs in the device. A signal from the column interconnect, which can be either the output of an LE or an input from an I/O pin, must be routed to the row interconnect before it can enter an LAB or EAB. Each row channel that is driven by an IOE or EAB can drive one specific column channel.

Access to row and column channels can be switched between LEs in adjacent pairs of LABs. For example, an LE in one LAB can drive the row and column channels normally driven by a particular LE in the adjacent LAB in the same row, and vice versa. This routing flexibility enables routing resources to be used more efficiently. See [Figure 11](#).

Table 50. EPF10K30, EPF10K40 & EPF10K50 Device EAB Internal Microparameters *Note (1)*

Symbol	-3 Speed Grade		-4 Speed Grade		Unit
	Min	Max	Min	Max	
$t_{EABDATA1}$		1.5		1.9	ns
$t_{EABDATA2}$		4.8		6.0	ns
t_{EABWE1}		1.0		1.2	ns
t_{EABWE2}		5.0		6.2	ns
t_{EABCLK}		1.0		2.2	ns
t_{EABCO}		0.5		0.6	ns
$t_{EABYPASS}$		1.5		1.9	ns
t_{EABSU}	1.5		1.8		ns
t_{EABH}	2.0		2.5		ns
t_{AA}		8.7		10.7	ns
t_{WP}	5.8		7.2		ns
t_{WDSU}	1.6		2.0		ns
t_{WDH}	0.3		0.4		ns
t_{WASU}	0.5		0.6		ns
t_{WAH}	1.0		1.2		ns
t_{WO}		5.0		6.2	ns
t_{DD}		5.0		6.2	ns
t_{EABOUT}		0.5		0.6	ns
t_{EABCH}	4.0		4.0		ns
t_{EABCL}	5.8		7.2		ns

Table 54. EPF10K50 Device Interconnect Timing Microparameters *Note (1)*

Symbol	-3 Speed Grade		-4 Speed Grade		Unit
	Min	Max	Min	Max	
$t_{DIN2IOE}$		8.4		10.2	ns
t_{DIN2LE}		3.6		4.8	ns
$t_{DIN2DATA}$		5.5		7.2	ns
$t_{DCLK2IOE}$		4.6		6.2	ns
$t_{DCLK2LE}$		3.6		4.8	ns
$t_{SAMELAB}$		0.3		0.3	ns
$t_{SAMEROW}$		3.3		3.7	ns
$t_{SAMECOLUMN}$		3.9		4.1	ns
$t_{DIFFROW}$		7.2		7.8	ns
$t_{TWOROWS}$		10.5		11.5	ns
$t_{LEPERIPH}$		7.5		8.2	ns
$t_{LABCARRY}$		0.4		0.6	ns
$t_{LABCASC}$		2.4		3.0	ns

Table 55. EPF10K30, EPF10K40 & EPF10K50 Device External Timing Parameters *Note (1)*

Symbol	-3 Speed Grade		-4 Speed Grade		Unit
	Min	Max	Min	Max	
t_{DRR}		17.2		21.1	ns
t_{INSU} (2), (3)	5.7		6.4		ns
t_{INH} (3)	0.0		0.0		ns
t_{OUTCO} (3)	2.0	8.8	2.0	11.2	ns

Table 56. EPF10K30, EPF10K40 & EPF10K50 Device External Bidirectional Timing Parameters *Note (1)*

Symbol	-3 Speed Grade		-4 Speed Grade		Unit
	Min	Max	Min	Max	
$t_{INSUBIDIR}$	4.1		4.6		ns
$t_{INHBIDIR}$	0.0		0.0		ns
$t_{OUTCOBIDIR}$	2.0	8.8	2.0	11.2	ns
$t_{XZBIDIR}$		12.3		15.0	ns
$t_{ZXBIDIR}$		12.3		15.0	ns

Table 60. EPF10K70 Device EAB Internal Timing Macroparameters *Note (1)*

Symbol	-2 Speed Grade		-3 Speed Grade		-4 Speed Grade		Unit
	Min	Max	Min	Max	Min	Max	
t_{EABAA}		12.1		13.7		17.0	ns
$t_{EABRCCOMB}$	12.1		13.7		17.0		ns
$t_{EABRCREG}$	8.6		9.7		11.9		ns
t_{EABWP}	5.2		5.8		7.2		ns
$t_{EABWCCOMB}$	6.5		7.3		9.0		ns
$t_{EABWCREG}$	11.6		13.0		16.0		ns
t_{EABDD}		8.8		10.0		12.5	ns
$t_{EABDATA CO}$		1.7		2.0		3.4	ns
$t_{EABDATASU}$	4.7		5.3		5.6		ns
$t_{EABDATAH}$	0.0		0.0		0.0		ns
$t_{EABWESU}$	4.9		5.5		5.8		ns
t_{EABWEH}	0.0		0.0		0.0		ns
$t_{EABWDSU}$	1.8		2.1		2.7		ns
t_{EABWDH}	0.0		0.0		0.0		ns
$t_{EABWASU}$	4.1		4.7		5.8		ns
t_{EABWAH}	0.0		0.0		0.0		ns
t_{EABWO}		8.4		9.5		11.8	ns

Table 68. EPF10K100 Device Interconnect Timing Microparameters *Note (1)*

Symbol	-3DX Speed Grade		-3 Speed Grade		-4 Speed Grade		Unit
	Min	Max	Min	Max	Min	Max	
$t_{DIN2IOE}$		10.3		10.3		12.2	ns
t_{DIN2LE}		4.8		4.8		6.0	ns
$t_{DIN2DATA}$		7.3		7.3		11.0	ns
$t_{DCLK2IOE}$ without ClockLock or ClockBoost circuitry		6.2		6.2		7.7	ns
$t_{DCLK2IOE}$ with ClockLock or ClockBoost circuitry		2.3		–		–	ns
$t_{DCLK2LE}$ without ClockLock or ClockBoost circuitry		4.8		4.8		6.0	ns
$t_{DCLK2LE}$ with ClockLock or ClockBoost circuitry		2.3		–		–	ns
$t_{SAMELAB}$		0.4		0.4		0.5	ns
$t_{SAMEROW}$		4.9		4.9		5.5	ns
$t_{SAMECOLUMN}$		5.1		5.1		5.4	ns
$t_{DIFFROW}$		10.0		10.0		10.9	ns
$t_{TWOROWS}$		14.9		14.9		16.4	ns
$t_{LEPERIPH}$		6.9		6.9		8.1	ns
$t_{LABCARRY}$		0.9		0.9		1.1	ns
$t_{LABCASC}$		3.0		3.0		3.2	ns

Table 72. EPF10K50V Device IOE Timing Microparameters *Note (1)*

Symbol	-1 Speed Grade		-2 Speed Grade		-3 Speed Grade		-4 Speed Grade		Unit
	Min	Max	Min	Max	Min	Max	Min	Max	
t_{IOD}		1.2		1.6		1.9		2.1	ns
t_{IOC}		0.3		0.4		0.5		0.5	ns
t_{IOCO}		0.3		0.3		0.4		0.4	ns
t_{IOCOMB}		0.0		0.0		0.0		0.0	ns
t_{IOSU}	2.8		2.8		3.4		3.9		ns
t_{IOH}	0.7		0.8		1.0		1.4		ns
t_{IOCLR}		0.5		0.6		0.7		0.7	ns
t_{OD1}		2.8		3.2		3.9		4.7	ns
t_{OD2}		—		—		—		—	ns
t_{OD3}		6.5		6.9		7.6		8.4	ns
t_{XZ}		2.8		3.1		3.8		4.6	ns
t_{ZX1}		2.8		3.1		3.8		4.6	ns
t_{ZX2}		—		—		—		—	ns
t_{ZX3}		6.5		6.8		7.5		8.3	ns
t_{INREG}		5.0		5.7		7.0		9.0	ns
t_{IOFD}		1.5		1.9		2.3		2.7	ns
t_{INCOMB}		1.5		1.9		2.3		2.7	ns

Table 74. EPF10K50V Device EAB Internal Timing Macroparameters *Note (1)*

Symbol	-1 Speed Grade		-2 Speed Grade		-3 Speed Grade		-4 Speed Grade		Unit
	Min	Max	Min	Max	Min	Max	Min	Max	
t_{EABAA}		9.5		13.6		16.5		20.8	ns
$t_{EABRCCOMB}$	9.5		13.6		16.5		20.8		ns
$t_{EABRCREG}$	6.1		8.8		10.8		13.4		ns
t_{EABWP}	6.0		4.9		6.0		7.4		ns
$t_{EABWCCOMB}$	6.2		6.1		7.5		9.2		ns
$t_{EABWCREG}$	12.0		11.6		14.2		17.4		ns
t_{EABDD}		6.8		9.7		11.8		14.9	ns
$t_{EABDATACO}$		1.0		1.4		1.8		2.2	ns
$t_{EABDATASU}$	5.3		4.6		5.6		6.9		ns
$t_{EABDATAH}$	0.0		0.0		0.0		0.0		ns
$t_{EABWESU}$	4.4		4.8		5.8		7.2		ns
t_{EABWEH}	0.0		0.0		0.0		0.0		ns
$t_{EABWDSU}$	1.8		1.1		1.4		2.1		ns
t_{EABWDH}	0.0		0.0		0.0		0.0		ns
$t_{EABWASU}$	4.5		4.6		5.6		7.4		ns
t_{EABWAH}	0.0		0.0		0.0		0.0		ns
t_{EABWO}		5.1		9.4		11.4		14.0	ns

Notes to tables:

- (1) All timing parameters are described in Tables 32 through 38 in this data sheet.
- (2) Using an LE to register the signal may provide a lower setup time.
- (3) This parameter is specified by characterization.

Tables 92 through 98 show EPF10K30A device internal and external timing parameters.

Table 92. EPF10K30A Device LE Timing Microparameters *Note (1)*

Symbol	-1 Speed Grade		-2 Speed Grade		-3 Speed Grade		Unit
	Min	Max	Min	Max	Min	Max	
t_{LUT}		0.8		1.1		1.5	ns
t_{CLUT}		0.6		0.7		1.0	ns
t_{RLUT}		1.2		1.5		2.0	ns
t_{PACKED}		0.6		0.6		1.0	ns
t_{EN}		1.3		1.5		2.0	ns
t_{CICO}		0.2		0.3		0.4	ns
t_{CGEN}		0.8		1.0		1.3	ns
t_{CGENR}		0.6		0.8		1.0	ns
t_{CASC}		0.9		1.1		1.4	ns
t_C		1.1		1.3		1.7	ns
t_{CO}		0.4		0.6		0.7	ns
t_{COMB}		0.6		0.7		0.9	ns
t_{SU}	0.9		0.9		1.4		ns
t_H	1.1		1.3		1.7		ns
t_{PRE}		0.5		0.6		0.8	ns
t_{CLR}		0.5		0.6		0.8	ns
t_{CH}	3.0		3.5		4.0		ns
t_{CL}	3.0		3.5		4.0		ns

Table 93. EPF10K30A Device IOE Timing Microparameters *Note (1) (Part 1 of 2)*

Symbol	-1 Speed Grade		-2 Speed Grade		-3 Speed Grade		Unit
	Min	Max	Min	Max	Min	Max	
t_{IOD}		2.2		2.6		3.4	ns
t_{IOC}		0.3		0.3		0.5	ns
t_{IOCO}		0.2		0.2		0.3	ns
t_{IOCOMB}		0.5		0.6		0.8	ns
t_{IOSU}	1.4		1.7		2.2		ns

Table 93. EPF10K30A Device IOE Timing Microparameters *Note (1) (Part 2 of 2)*

Symbol	-1 Speed Grade		-2 Speed Grade		-3 Speed Grade		Unit
	Min	Max	Min	Max	Min	Max	
t_{IOH}	0.9		1.1		1.4		ns
t_{IOCLR}		0.7		0.8		1.0	ns
t_{OD1}		1.9		2.2		2.9	ns
t_{OD2}		4.8		5.6		7.3	ns
t_{OD3}		7.0		8.2		10.8	ns
t_{XZ}		2.2		2.6		3.4	ns
t_{ZX1}		2.2		2.6		3.4	ns
t_{ZX2}		5.1		6.0		7.8	ns
t_{ZX3}		7.3		8.6		11.3	ns
t_{INREG}		4.4		5.2		6.8	ns
t_{IOFD}		3.8		4.5		5.9	ns
t_{INCOMB}		3.8		4.5		5.9	ns

Table 101. EPF10K100A Device EAB Internal Microparameters *Note (1)*

Symbol	-1 Speed Grade		-2 Speed Grade		-3 Speed Grade		Unit
	Min	Max	Min	Max	Min	Max	
$t_{EABDATA1}$		1.8		2.1		2.4	ns
$t_{EABDATA2}$		3.2		3.7		4.4	ns
t_{EABWE1}		0.8		0.9		1.1	ns
t_{EABWE2}		2.3		2.7		3.1	ns
t_{EABCLK}		0.8		0.9		1.1	ns
t_{EABCO}		1.0		1.1		1.4	ns
$t_{EABYPASS}$		0.3		0.3		0.4	ns
t_{EABSU}	1.3		1.5		1.8		ns
t_{EABH}	0.4		0.5		0.5		ns
t_{AA}		4.1		4.8		5.6	ns
t_{WP}	3.2		3.7		4.4		ns
t_{WDSU}	2.4		2.8		3.3		ns
t_{WDH}	0.2		0.2		0.3		ns
t_{WASU}	0.2		0.2		0.3		ns
t_{WAH}	0.0		0.0		0.0		ns
t_{WO}		3.4		3.9		4.6	ns
t_{DD}		3.4		3.9		4.6	ns
t_{EABOUT}		0.3		0.3		0.4	ns
t_{EABCH}	2.5		3.5		4.0		ns
t_{EABCL}	3.2		3.7		4.4		ns

Table 103. EPF10K100A Device Interconnect Timing Microparameters *Note (1)*

Symbol	-1 Speed Grade		-2 Speed Grade		-3 Speed Grade		Unit
	Min	Max	Min	Max	Min	Max	
$t_{DIN2IOE}$		4.8		5.4		6.0	ns
t_{DIN2LE}		2.0		2.4		2.7	ns
$t_{DIN2DATA}$		2.4		2.7		2.9	ns
$t_{DCLK2IOE}$		2.6		3.0		3.5	ns
$t_{DCLK2LE}$		2.0		2.4		2.7	ns
$t_{SAMELAB}$		0.1		0.1		0.1	ns
$t_{SAMEROW}$		1.5		1.7		1.9	ns
$t_{SAMECOLUMN}$		5.5		6.5		7.4	ns
$t_{DIFFROW}$		7.0		8.2		9.3	ns
$t_{TWOROWS}$		8.5		9.9		11.2	ns
$t_{LEPERIPH}$		3.9		4.2		4.5	ns
$t_{LABCARRY}$		0.2		0.2		0.3	ns
$t_{LABCASC}$		0.4		0.5		0.6	ns

Table 104. EPF10K100A Device External Timing Parameters *Note (1)*

Symbol	-1 Speed Grade		-2 Speed Grade		-3 Speed Grade		Unit
	Min	Max	Min	Max	Min	Max	
t_{DRR}		12.5		14.5		17.0	ns
t_{INSU} (2), (3)	3.7		4.5		5.1		ns
t_{INH} (3)	0.0		0.0		0.0		ns
t_{OUTCO} (3)	2.0	5.3	2.0	6.1	2.0	7.2	ns

Table 105. EPF10K100A Device External Bidirectional Timing Parameters *Note (1)*

Symbol	-1 Speed Grade		-2 Speed Grade		-3 Speed Grade		Unit
	Min	Max	Min	Max	Min	Max	
$t_{INSUBIDIR}$	4.9		5.8		6.8		ns
$t_{INHBIDIR}$	0.0		0.0		0.0		ns
$t_{OUTCOBIDIR}$	2.0	5.3	2.0	6.1	2.0	7.2	ns
$t_{XZBIDIR}$		7.4		8.6		10.1	ns
$t_{ZXBIDIR}$		7.4		8.6		10.1	ns

Table 108. EPF10K250A Device EAB Internal Microparameters *Note (1)*

Symbol	-1 Speed Grade		-2 Speed Grade		-3 Speed Grade		Unit
	Min	Max	Min	Max	Min	Max	
$t_{EABDATA1}$		1.3		1.5		1.7	ns
$t_{EABDATA2}$		1.3		1.5		1.7	ns
t_{EABWE1}		0.9		1.1		1.3	ns
t_{EABWE2}		5.0		5.7		6.7	ns
t_{EABCLK}		0.6		0.7		0.8	ns
t_{EABCO}		0.0		0.0		0.0	ns
$t_{EABYPASS}$		0.1		0.1		0.2	ns
t_{EABSU}	3.8		4.3		5.0		ns
t_{EABH}	0.7		0.8		0.9		ns
t_{AA}		4.5		5.0		5.9	ns
t_{WP}	5.6		6.4		7.5		ns
t_{WDSU}	1.3		1.4		1.7		ns
t_{WDH}	0.1		0.1		0.2		ns
t_{WASU}	0.1		0.1		0.2		ns
t_{WAH}	0.1		0.1		0.2		ns
t_{WO}		4.1		4.6		5.5	ns
t_{DD}		4.1		4.6		5.5	ns
t_{EABOUT}		0.1		0.1		0.2	ns
t_{EABCH}	2.5		3.0		3.5		ns
t_{EABCL}	5.6		6.4		7.5		ns

- f_{MAX} = Maximum operating frequency in MHz
 N = Total number of logic cells used in the device
 tog_{LC} = Average percent of logic cells toggling at each clock (typically 12.5%)
 K = Constant, shown in [Tables 114 and 115](#)

Table 114. FLEX 10K K Constant Values

Device	K Value
EPF10K10	82
EPF10K20	89
EPF10K30	88
EPF10K40	92
EPF10K50	95
EPF10K70	85
EPF10K100	88

Table 115. FLEX 10KA K Constant Values

Device	K Value
EPF10K10A	17
EPF10K30A	17
EPF10K50V	19
EPF10K100A	19
EPF10K130V	22
EPF10K250A	23

This calculation provides an I_{CC} estimate based on typical conditions with no output load. The actual I_{CC} should be verified during operation because this measurement is sensitive to the actual pattern in the device and the environmental operating conditions.

To better reflect actual designs, the power model (and the constant K in the power calculation equations) for continuous interconnect FLEX devices assumes that logic cells drive FastTrack Interconnect channels. In contrast, the power model of segmented FPGAs assumes that all logic cells drive only one short interconnect segment. This assumption may lead to inaccurate results, compared to measured power consumption for an actual design in a segmented interconnect FPGA.

[Figure 32](#) shows the relationship between the current and operating frequency of FLEX 10K devices.

Multiple FLEX 10K devices can be configured in any of the five configuration schemes by connecting the configuration enable (nCE) and configuration enable output (nCEO) pins on each device.

Table 116. Data Sources for Configuration

Configuration Scheme	Data Source
Configuration device	EPC1, EPC2, EPC16, or EPC1441 configuration device
Passive serial (PS)	BitBlaster, MasterBlaster, or ByteBlasterMV download cable, or serial data source
Passive parallel asynchronous (PPA)	Parallel data source
Passive parallel synchronous (PPS)	Parallel data source
JTAG	BitBlaster, MasterBlaster, or ByteBlasterMV download cable, or microprocessor with Jam STAPL file or Jam Byte-Code file

Device Pin-Outs

See the Altera web site (<http://www.altera.com>) or the Altera Digital Library for pin-out information.

Revision History

The information contained in the *FLEX 10K Embedded Programmable Logic Device Family Data Sheet* version 4.2 supersedes information published in previous versions.

Version 4.2 Changes

The following change was made to version 4.2 of the *FLEX 10K Embedded Programmable Logic Device Family Data Sheet*: updated [Figure 13](#).

Version 4.1 Changes

The following changes were made to version 4.1 of the *FLEX 10K Embedded Programmable Logic Device Family Data Sheet*.

- Updated General Description section
- Updated I/O Element section
- Updated SameFrame Pin-Outs section
- Updated Figure 16
- Updated Tables 13 and 116
- Added Note 9 to Table 19
- Added Note 10 to Table 24
- Added Note 10 to Table 28